

ABSTRACT OF THE DISCLOSURE

When an electronic component is mounted on a substrate, the electronic component is first placed on the substrate with a solid support interposed between the electronic component and the substrate. The solid support serves to space a terminal conductor of the electronic component from a corresponding terminal pad on the substrate. A conductive bonding material is then melted on the terminal pad. The melted conductive bonding material gets exposed to the peripheral atmosphere over a larger area. Even if a bubble is generated within the melted conductive bonding material, the bubble is allowed to easily get out of the melted conductive bonding material. Removal of the gas is promoted in the melted conductive bonding material. The solid support is subsequently melted. The electronic component is moved down toward the substrate, thereby contacting the terminal conductor with the melted conductive bonding material on the corresponding terminal pad. Removal of the gas in this manner leads to improvement in the strength of bonding between the substrate and the electronic component.